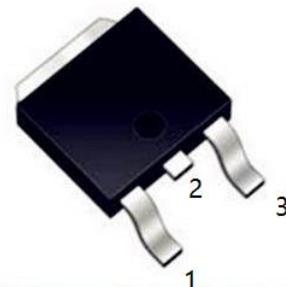


**V<sub>RRM</sub>** = 650 V

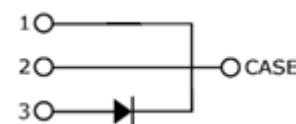
**I<sub>F</sub>(T<sub>c</sub>=145°C)** = 8.3 A

**Q<sub>c</sub>** = 27 nC



### Features:

- Extremely low reverse current
- No reverse recovery current
- Temperature independent switching
- Positive temperature coefficient on V<sub>F</sub>
- Excellent surge current capability
- Low Capacitive charge



### Benefits

- Essentially No switching losses
- System efficiency improvement over Si Diodes
- Increased power density
- Enabling higher switching frequency
- Reduction of Heat Sink Requirements
- System Cost savings due to smaller magnetics
- Reduced EMI



### Applications

- Switch Mode Power Supplies (SMPS)
- Uninterruptable power supplies
- Motor Drivers
- Power Factor Correction

### Package Pin definitions

- Pin1-Cathode
- Pin2-Cathode
- Pin3-Anode

### Package Parameters

Part Number	Marking	Package
B1D08065E	B1D08065E	TO-252-3

**Maximum ratings**

Symbol	Parameter	Test conditions	Value	Unit
$V_{RRM}$	Repetitive Peak Reverse Voltage		650	V
$V_{RSM}$	Surge Peak Reverse Voltage		650	V
$I_F$	Continuous Forward Current	Tc=25°C Tc=135°C Tc=145°C	21 10 8.3	A
$I_{FSM}$	Non-Repetitive Forward Surge Current	Tc=25°C , t <sub>p</sub> =10ms, sine halfwave	56	A
$\int i^2 dt$	i <sup>2</sup> t Value	Tc=25°C , t <sub>p</sub> =10ms	15.68	A <sup>2</sup> S
$P_{tot}$	Power Dissipation	Tc=25°C Tc=110°C	94 40	W
$T_j$	Operating junction temperature		-55~175	°C
$T_{stg}$	Storage temperature		-55~135	°C

**Thermal Characteristics**

Symbol	Parameter	Value			Unit
		Min.	Typ.	Max.	
$R_{th(jc)}$	Thermal resistance from junction to case		1.589		K/W

**Electrical Characteristics****Static Characteristics (T<sub>j</sub>=25°C unless otherwise specified)**

<b>Symbol</b>	<b>Parameter</b>	<b>Test conditions</b>	<b>Value</b>			<b>Unit</b>
			<b>Min.</b>	<b>Typ.</b>	<b>Max.</b>	
V <sub>DC</sub>	DC blocking voltage	T <sub>j</sub> =25°C	650			V
V <sub>F</sub>	Diode forward voltage	I <sub>F</sub> =8A T <sub>j</sub> =25°C I <sub>F</sub> =8A T <sub>j</sub> =175°C		1.45 1.9		V
I <sub>R</sub>	Reverse current	V <sub>R</sub> =650V T <sub>j</sub> =25°C V <sub>R</sub> =650V T <sub>j</sub> =175°C		0.05 3		μA

**Dynamic Characteristics (T<sub>j</sub>=25°C unless otherwise specified)**

<b>Symbol</b>	<b>Parameter</b>	<b>Test conditions</b>	<b>Value</b>			<b>Unit</b>
			<b>Min.</b>	<b>Typ.</b>	<b>Max.</b>	
Q <sub>C</sub>	Total capacitive charge	V <sub>R</sub> =400V T <sub>j</sub> =25°C $Q_C = \int_0^{V_R} C(V)dV$		27		nC
C	Total Capacitance	V <sub>R</sub> =1V f=1MHz V <sub>R</sub> =300V f=1MHz V <sub>R</sub> =600V f=1MHz		380 50.9 50.5		pF

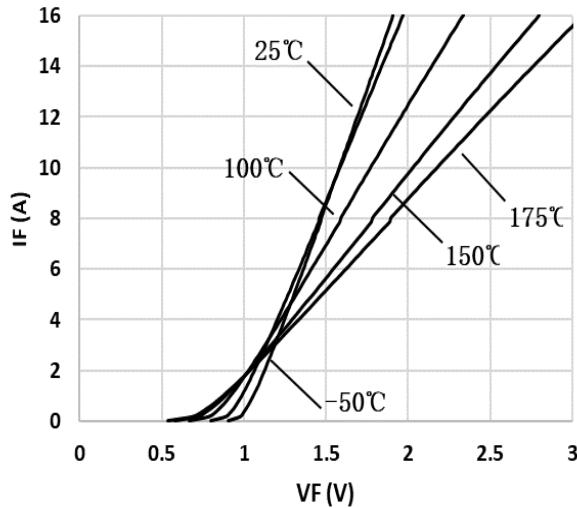


Figure 1. Typical forward characteristics

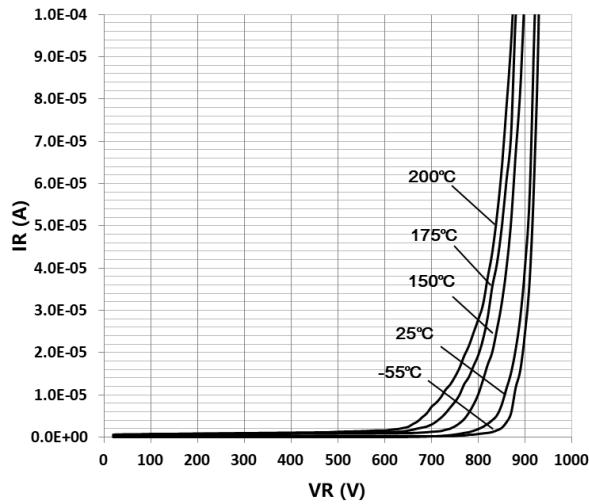


Figure 2. Typical reverse current as function of reverse voltage

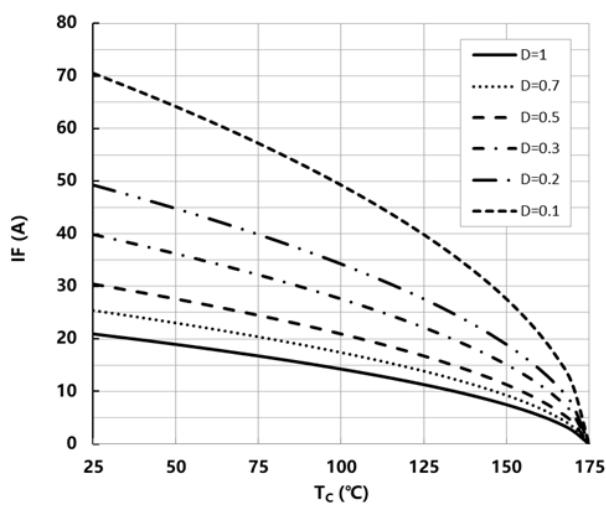
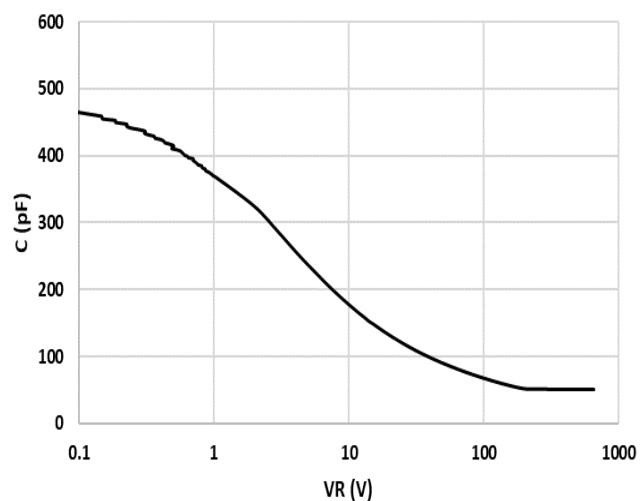


Figure 3. Diode forward current as function of temperature, D=duty cycle

Figure 4. Typical capacitance as function of reverse voltage,  $C=f(V_R)$ ;  $T_j=25^\circ\text{C}$ ;  $f=1\text{ MHz}$

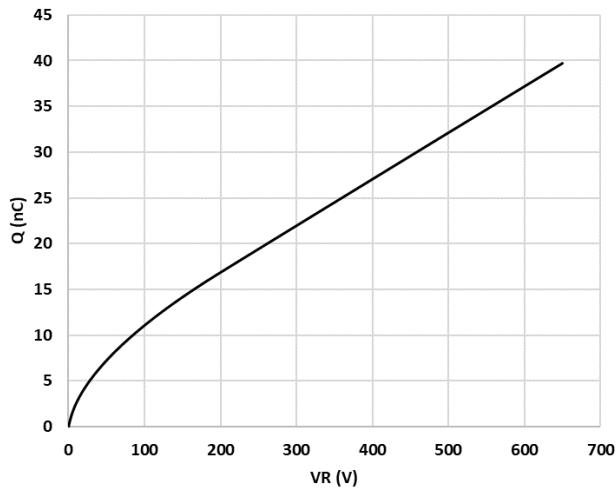


Figure 5. Typical reverse charge as function of reverse voltage

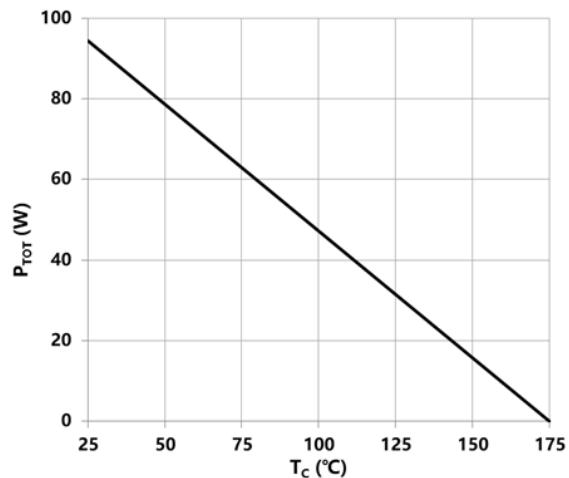
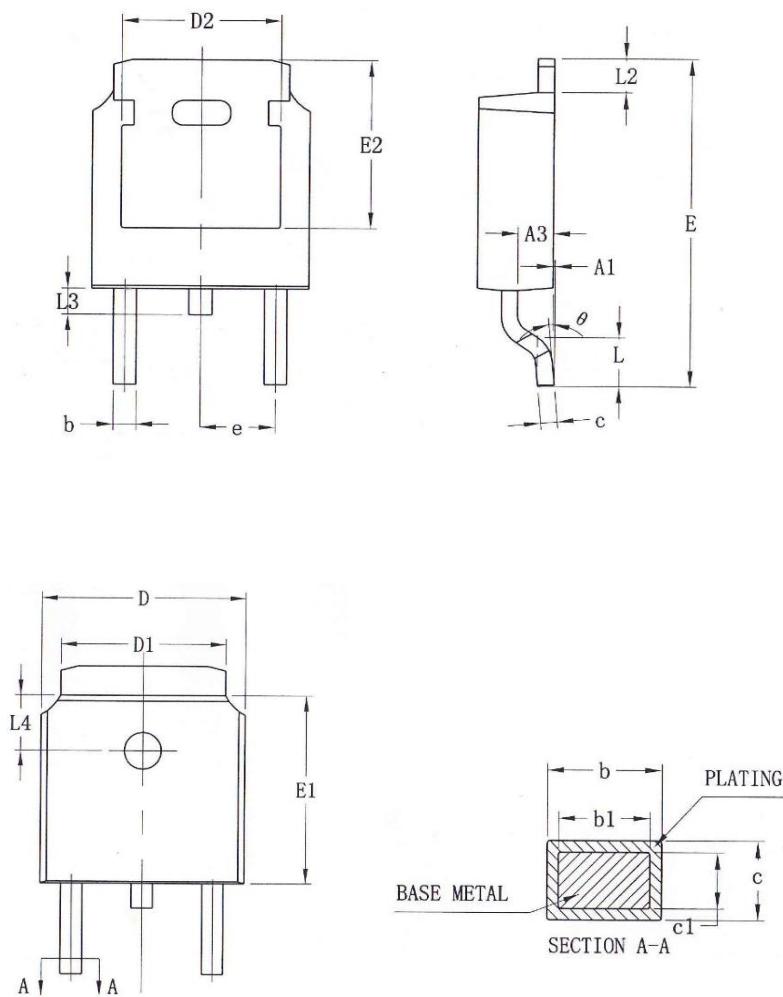


Figure 6. Power dissipation as function of case temperature

**Package Dimensions**


SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A1	0.00	—	0.10
A2	2.20	2.30	2.40
A3	1.02	1.07	1.12
b	0.74	—	0.82
b1	0.73	0.76	0.79
c	0.51	—	0.55
c1	0.50	0.51	0.52
D	6.50	6.60	6.70
D1	5.33REF		
D2	4.83REF		
E	9.90	10.10	10.30
E1	6.00	6.10	6.20
E2	5.30REF		
e	2.286BSC		
L	1.40	1.50	1.60
L2	0.90	—	1.25
L3	0.60	0.80	1.00
L4	1.70	1.80	1.90
θ	0	8°	

**Revision History:**

**2019-07-01, Rev.1.0**

**Previous Revision:**

Rev.1.0 Release of datasheet

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**Shenzhen, China**  
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